



Title: METHOD OF IMPLANTING
COPPER BARRIER MATERIAL TO
IMPROVE ELECTRICAL PERFORMANCE

Inventor(s): Besser et al.

Appl. No.: 09/994,397

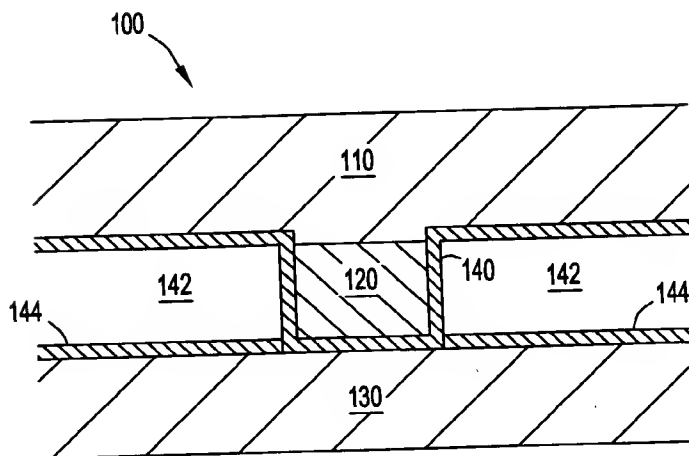


FIG. 1
PRIOR ART

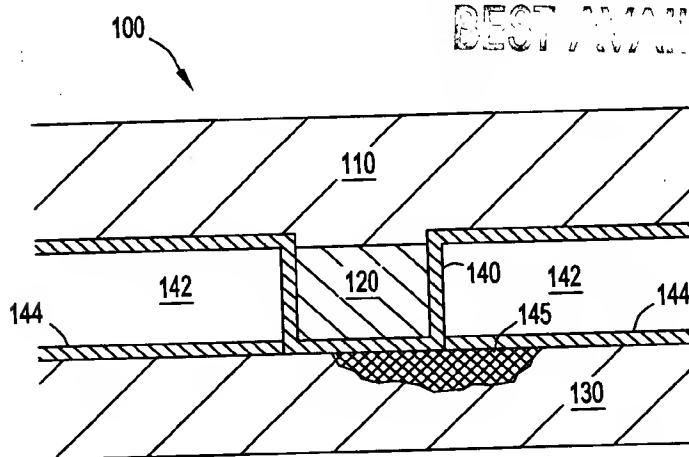


FIG. 2
PRIOR ART



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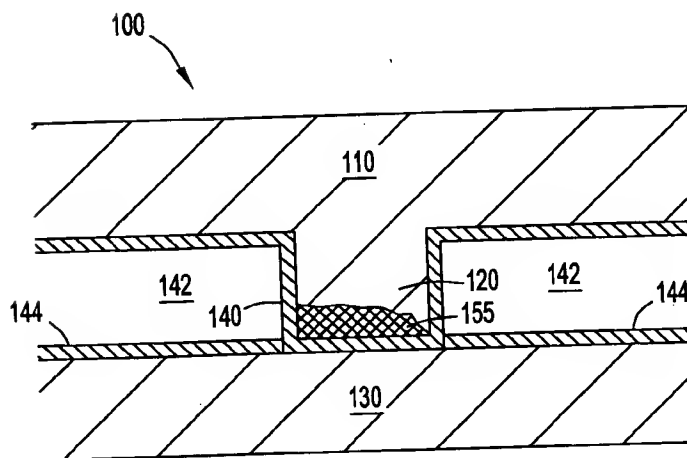


FIG. 3
PRIOR ART

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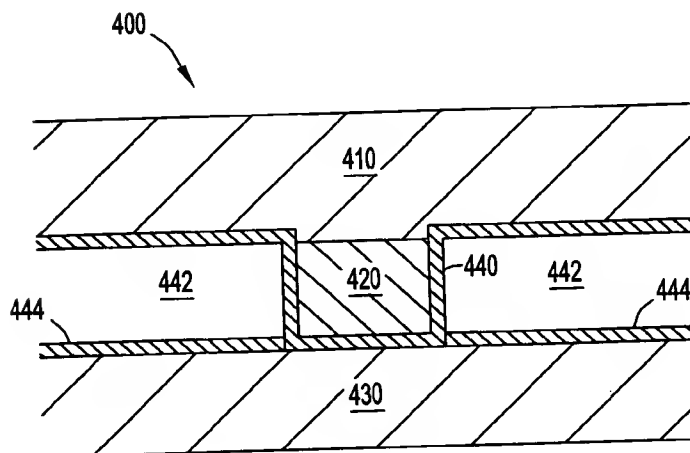


FIG. 4



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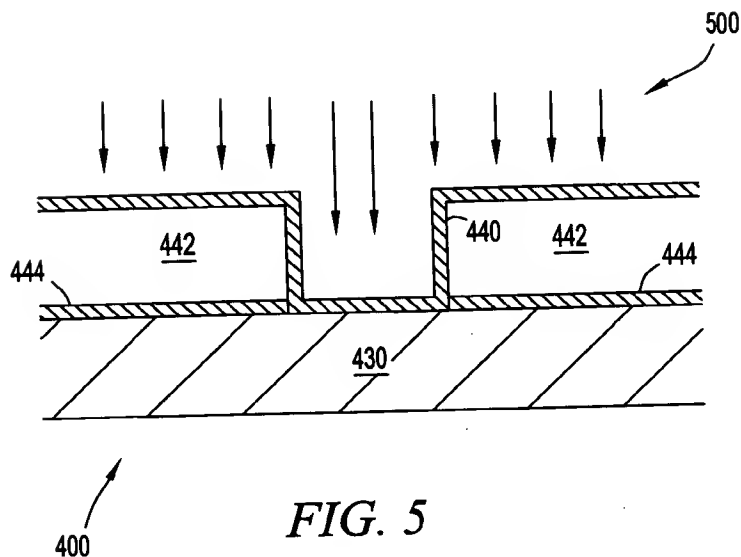


FIG. 5

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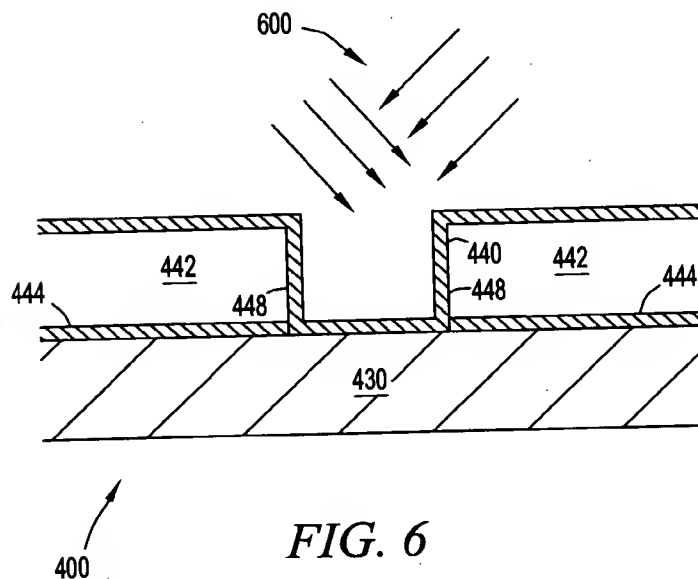


FIG. 6